

## 1. Introduction

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This document deals with the mounting and soldering of CATV modules.

## 2. Mounting and soldering recommendations

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### 2.1 Mounting

The heatsink surface must be flat, free of burrs and oxidation and be parallel to the mounting surface.

The heatsink, mounting base and ground leads should be properly RF-grounded.

Heatsink compound should be applied sparingly and evenly on the mounting base. Suitable heatsink compounds are Dow Corning 340, Eccotherm TC-5 (E and C) and Wakefield 120.

When mounting CATV hybrid modules, the UNC screws must first be turned finger-tight. The screws should then be tightened to within the tolerance 0.5 Nm minimum and 0.7 Nm maximum.

### 2.2 Soldering

Modules may be soldered directly into a circuit using a soldering iron with a maximum temperature of 260 °C for not more than 3 seconds when the soldered joints are a minimum of 3 mm from the module.

### 3. Disclaimers

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